

Notice of References Cited	Application/Control No. 09/851,313		Applicant(s)/Patent Under Reexamination USAMI, TATSUYA	
	Examiner JULIO J. MALDONADO		Art Unit 2823	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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*	B	US-6,333,257	12-2001	Aoi, Nobuo	438/626
*	C	US-6,218,317	04-2001	Allada et al.	438/780
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	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Chen et al., Effects of Slurry formulations on chemical-mechanical polishing of low dielectric constant polysiloxanes: hydrido-organo siloxane and methyl silsesquioxane; J. Vac. Sci. Technol. B 18(1), Jan/Feb 2000, pages 201-207.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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